

Teesha Jenkins

From: Telecommunications Industry Association (TIA) <standards@tiaonline.org>
Sent: Monday, October 4, 2021 9:12 PM
To: jscanlan@ipvm.com
Cc: Cheryl Thibideau; TIA Standards; MembershipMailbox TIA; Zachary Carr; Sabrina Sheth
Subject: TIA Engineering Committee Application

Dear John,

Thank you for IPVM's interest in joining the U.S. standards development process.

Your TIA Engineering Committee application has been submitted for review. TIA staff will contact you to provide additional details about the committee you are interested in such as upcoming meetings and conferences, current standards work as well as the membership fees.

We look forward to IPVM's active participation in the TIA standards development process.

Your application included the following information:

Name: John Scanlan

Title: Research Engineer

Company: IPVM

Address: 3713 Linden Street

Address (line 2): Suite B

City: Bethlehem

State: PA

Zip: 18020

Country: United States

Phone: 5708017999

Email: jscanlan@ipvm.com

Company Revenue: 2500000

Committee Interest: TR-42

Technology and Standards Department and staff look forward to helping you achieve your goal to join TIA's Standards Development process!

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